

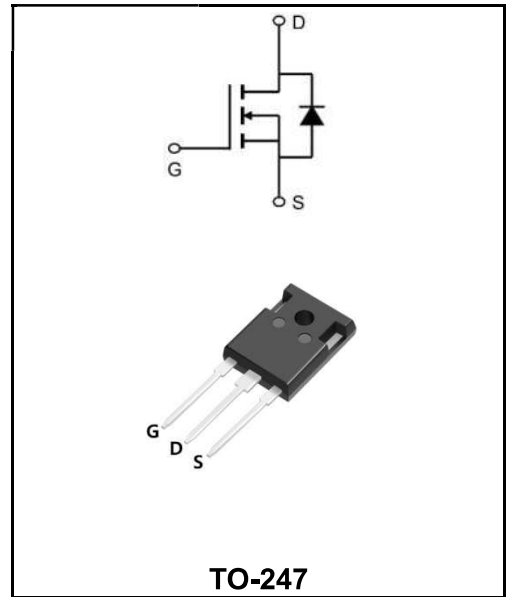
**250V N-CHANNEL ENHANCEMENT MODE MOSFET**

**MAIN CHARACTERISTICS**

<b>I<sub>D</sub></b>	50A
<b>V<sub>DSS</sub></b>	250V
<b>R<sub>DS(on)-typ(@V<sub>GS</sub>=10V)</sub></b>	< 85mΩ( <b>Type:70mΩ</b> )

**Application**

- ◆Uninterruptible Power Supply(UPS)
- ◆Power Factor Correction (PFC)



**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW50N25AP	TO-247	YFW 50N25AP XXXXX	600PCS/Tube

**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage(V <sub>GS</sub> =0V)	<b>V<sub>DS</sub></b>	250	<b>V</b>
Continuous Drain Current	<b>I<sub>D</sub></b>	50	<b>A</b>
Pulsed Drain Current	<b>I<sub>DM</sub></b>	180	<b>A</b>
Gate - Source Voltage	<b>V<sub>GS</sub></b>	±30	<b>V</b>
Single Pulse Avalanche Energy	<b>E<sub>AS</sub></b>	973	<b>mJ</b>
Avalanche Current	<b>I<sub>AS</sub></b>	36	<b>A</b>
Repetitive Avalanche Energy	<b>E<sub>AR</sub></b>	584	<b>mJ</b>
Power Dissipation (T <sub>c</sub> =25°C)	<b>P<sub>D</sub></b>	65	<b>W</b>
Operating Junction and Storage Temperature Range	<b>T<sub>J</sub> ,T<sub>STG</sub></b>	-55 to +150	<b>°C</b>
Thermal Resistance, Junction-case	<b>R<sub>θJC</sub></b>	0.89	<b>K/W</b>
Thermal Resistance, Junction ambient	<b>R<sub>θJA</sub></b>	60	<b>K/W</b>

**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	<b>V(BR)DSS</b>	250	-	-	<b>V</b>
Zero Gate Voltage Drain Current	$V_{DS}=250V, V_{GS}=0V, T_J=25^\circ C$	<b>I<sub>DSS</sub></b>	-	-	1	<b>μA</b>
Gate- Source Leakage	$V_{GS}=\pm 30V$	<b>I<sub>GSS</sub></b>	-	-	±100	<b>nA</b>
Gate Source Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	<b>V<sub>GS(th)</sub></b>	2	-	4	<b>V</b>
Drain-Source On-Resistance (Note3)	$V_{GS}=10V, I_D=22.5A$	<b>R<sub>DS(ON)</sub></b>	-	70	85	<b>mΩ</b>
Input Capacitance	$V_{DS}=25V$ $V_{GS}=0V$ $f=1MHz$	<b>C<sub>iss</sub></b>	-	3539	-	<b>pF</b>
Output Capacitance		<b>C<sub>oss</sub></b>	-	535	-	
Reverse Transfer Capacitance		<b>C<sub>rss</sub></b>	-	309	-	
Total Gate Charge	$V_{DD}=200V$ $I_D=45A$ $V_{GS}=10V$	<b>Q<sub>g</sub></b>	-	244	-	<b>nC</b>
Gate-Source Charge		<b>Q<sub>gs</sub></b>	-	16	-	
Gate-Drain Charge		<b>Q<sub>gd</sub></b>	-	143	-	
Turn-on delay time	$V_{DD}=125V$ $I_D=45A$ $R_G=25\Omega$	<b>t<sub>d(on)</sub></b>	-	57	-	<b>ns</b>
Turn-on Rise Time		<b>T<sub>r</sub></b>	-	145	-	
Turn-Off Delay Time		<b>t<sub>d(OFF)</sub></b>	-	960	-	
Turn-on Fall Time		<b>t<sub>f</sub></b>	-	235	-	
Continuous Body Diode Current	$T_C=25^\circ C$	<b>I<sub>S</sub></b>	-	-	45	<b>A</b>
Pulsed Diode Forward Current		<b>I<sub>SM</sub></b>	-	-	180	
Body Diode Voltage	$V_{GS}=0V, I_{SD}=22.5A, T_J=25^\circ C$	<b>V<sub>SD</sub></b>	-	-	1.4	<b>V</b>
Reverse Recovery Time	$V_{GS}=0V, I_S=10A,$ $di_{SD}/dt=100A/\mu s$	<b>t<sub>rr</sub></b>	-	264	-	<b>ns</b>
Reverse Recovery Charge		<b>Q<sub>rr</sub></b>	-	3	-	<b>nC</b>

**Notes**

- 1、Repetitive Rating: Pulse width limited by maximum junction temperature
- 2、L = 1.0mH, VDD = 50V, RG = 25 Ω, Starting TJ = 25 °C
- 3、Pulse Test: Pulse width ≤ 300μs, Duty Cycle ≤ 1%

Ratings and Characteristic Curves

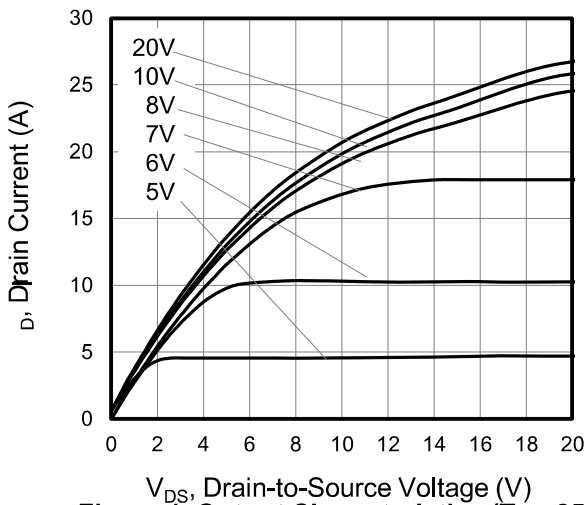


Figure 1. Output Characteristics ( $T_J = 25^\circ\text{C}$ )

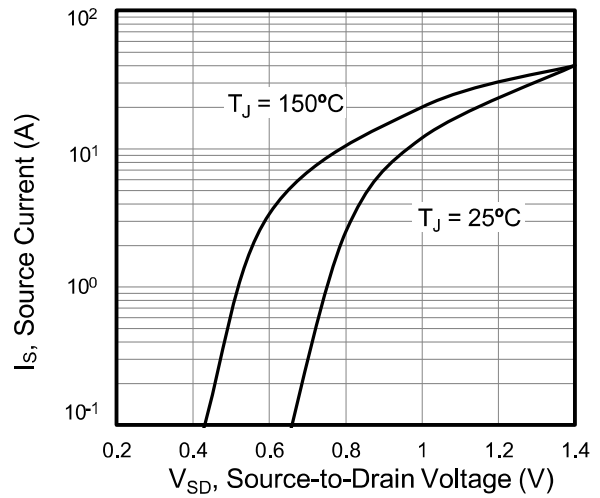


Figure 2. Body Diode Forward Voltage

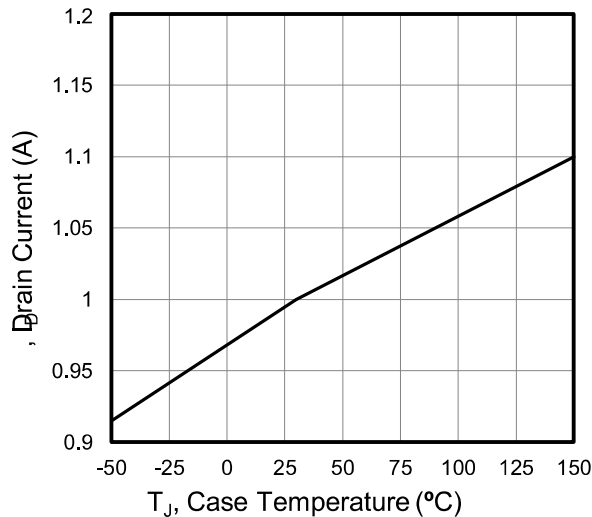


Figure 3. Drain Current vs. Temperature

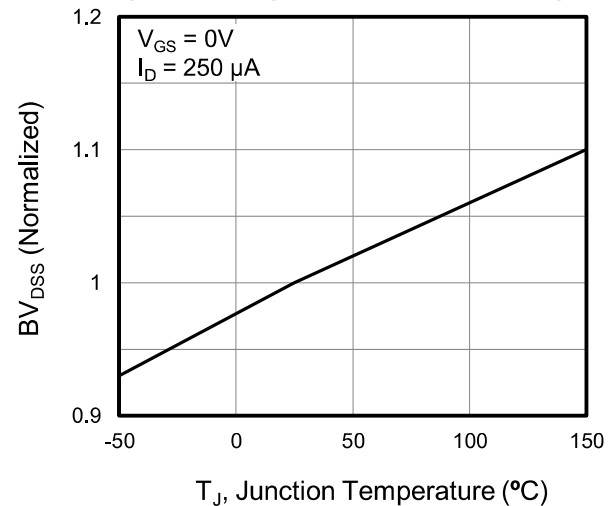


Figure 4.  $BV_{DSS}$  Variation vs. Temperature

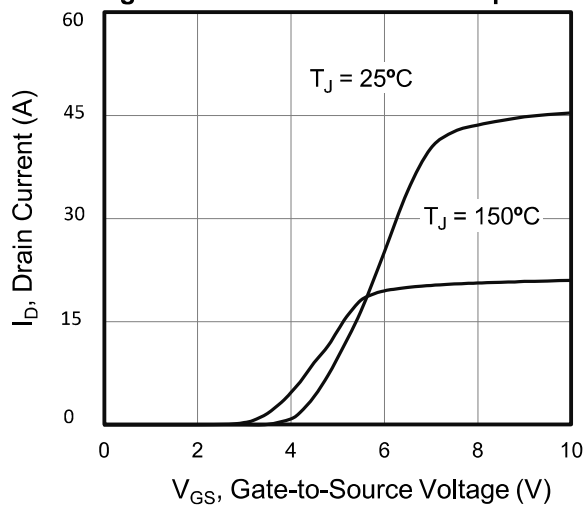


Figure 5. Transfer Characteristics

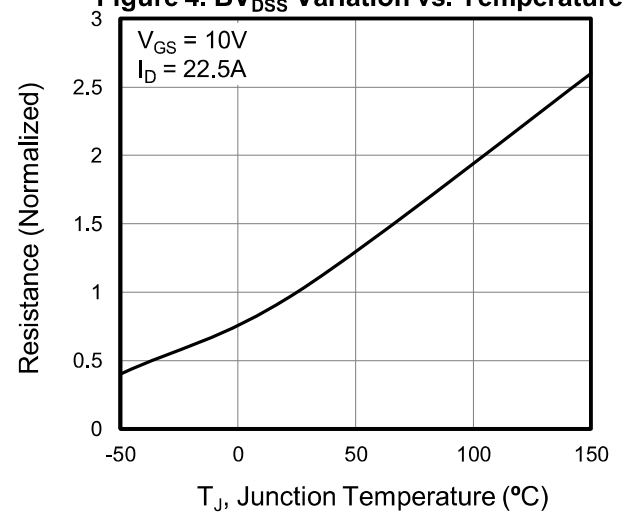
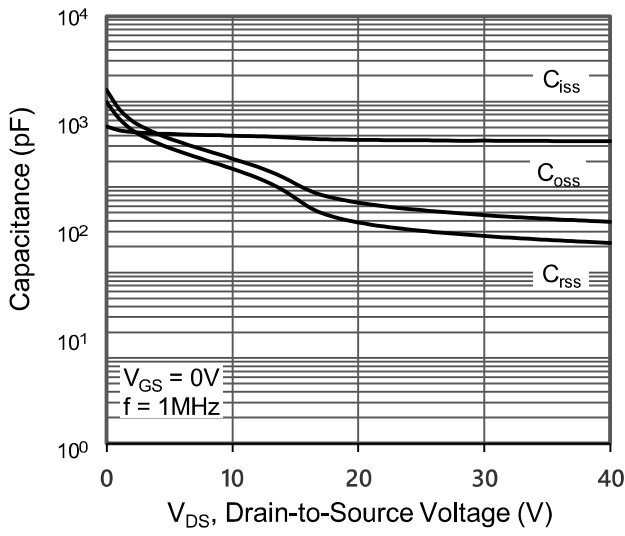
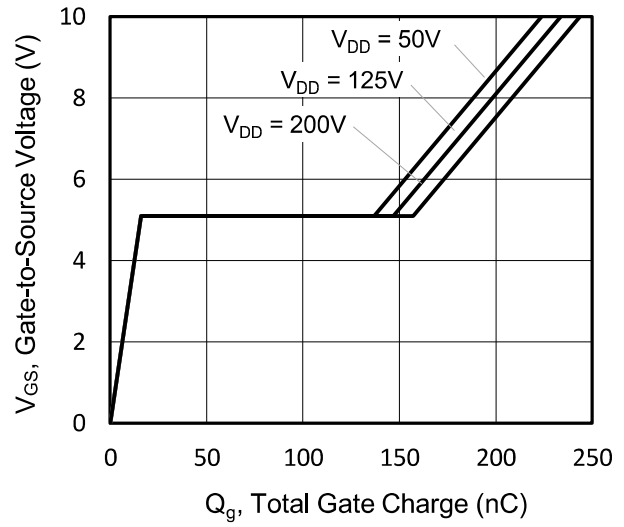


Figure 6. On-Resistance vs. Temperature

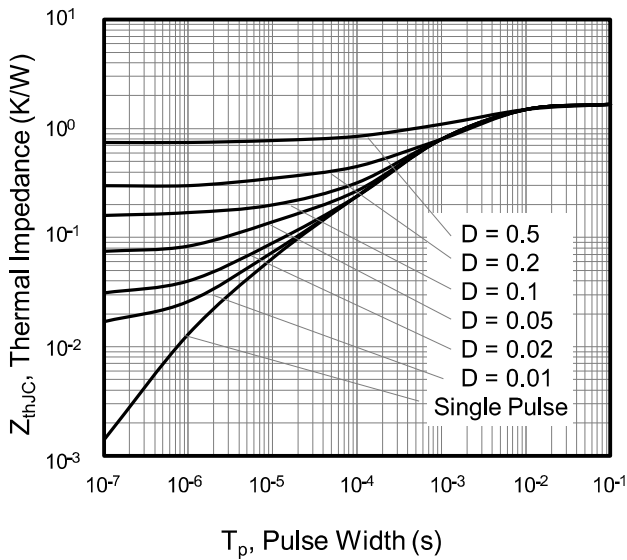
**Ratings and Characteristic Curves**



**Figure 7. Capacitance**

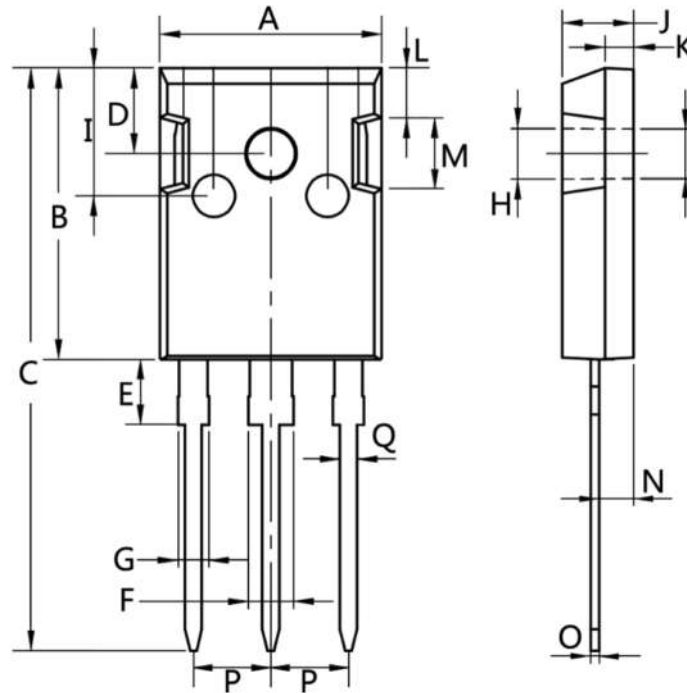


**Figure 8. Gate Charge**



**Figure 10. Transient Thermal Impedance**

TO-247



Dim.	Min.	Max.
A	15.0	16.0
B	20.0	21.0
C	41.0	42.0
D	5.0	6.0
E	4.0	5.0
F	2.5	3.5
G	1.75	2.5
H	3.0	3.5
I	8.0	10.0
J	4.9	5.1
K	1.9	2.1
L	3.5	4.0
M	4.75	5.25
N	2.0	3.0
O	0.55	0.75
P	Typ 5.08	
Q	1.2	1.3